

# BRGBJ3510

Rev.A Apr.-2016

## 描述 / Descriptions

整流桥，反向电压：1000V，正向电流：35A，GBJ 封装。

Silicon Bridge Rectifiers, Reverse Voltage:1000V,Forward Current:35A,GBJ package.

## 特征 / Features

浪涌额定过载电流 400A，塑料材料阻燃等级 UL94-V0。

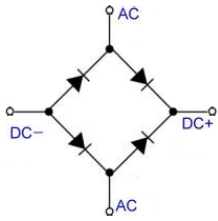
Surge overload rating -400 amperes peak,Plastic material has UL94-V0.

## 用途 / Applications

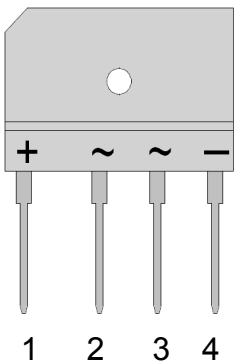
一般用途。

General purpose.

## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



PIN1 : DC+

PIN2 : AC

PIN 3 : AC

PIN 4 : DC-

## 放大及印章代码 / $h_{FE}$ Classifications & Marking

见印章说明。 See Marking Instructions

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	1000	V
Maximum RMS Voltage	$V_{RMS}$	700	V
Maximum DC Blocking Voltage	$V_{DC}$	1000	V
Maximum Average Forward Current	$I_{(AV)}$	35	A
Peak forward surge current	$I_{FSM}$	400	A
I2t Rating for Fusing (t<8.3ms)	I2t	510	A2s
Typical Junction Capacitance(Note1)	CJ	85	pF
Typical Thermal Resistance (Note2)	$R_{\theta Jc}$	0.6	°C/W
Junction Temperature Range	$T_j$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C

NOTE:

1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2.Device mounted on 300mm\*300mm\*1.6mm cu plate heatsink.

**电性能参数 / Electrical Characteristics(Ta=25°C)**

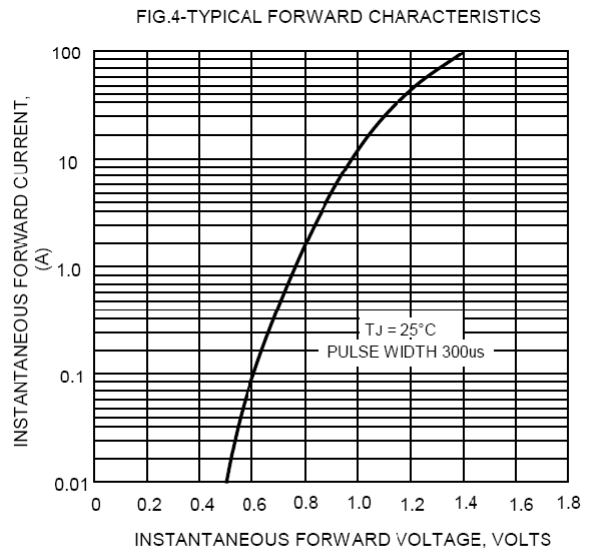
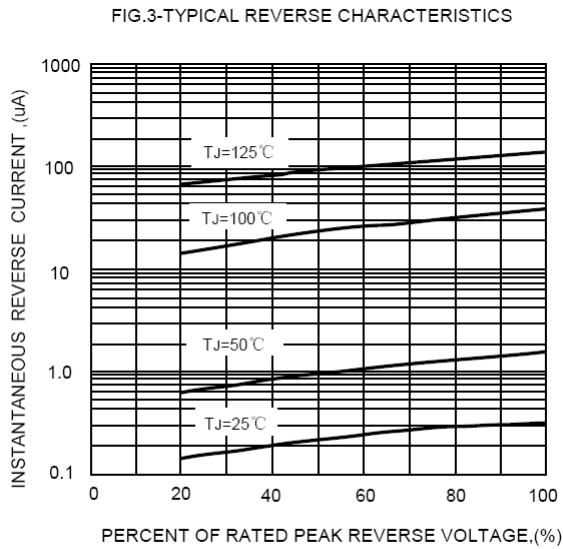
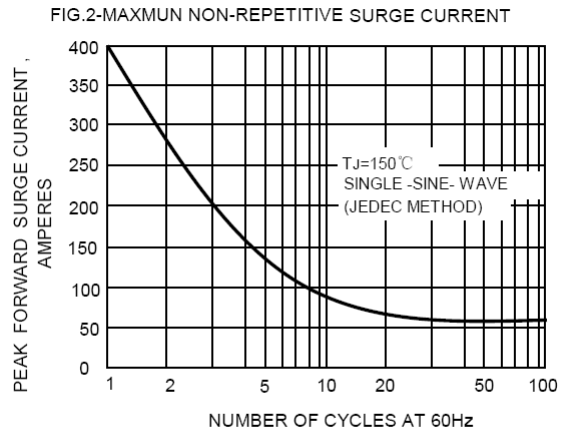
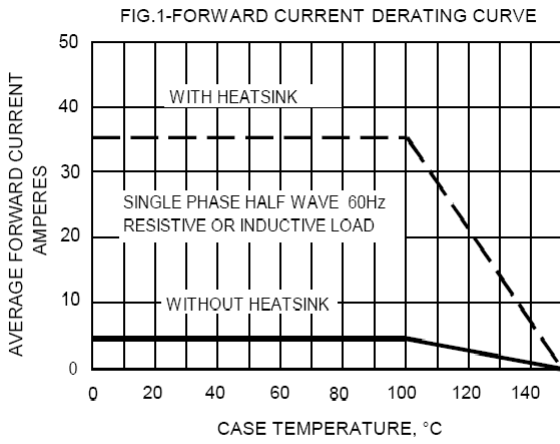
参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Reverse Voltage	$V_R$	$I_R=0.1mA$	1000			V
Forward Voltage	$V_F$	$I_F=17.5A$ $T_J=25^\circ C$			1.1	V
Instantaneous Reverse Current	$I_R$ (Note 1)	$V_R=1000V$ $T_J=25^\circ C$			10	$\mu A$
		$V_R=1000V$ $T_J=125^\circ C$			500	

注/Notes:

1. 使用极短的测试时间,以尽量减少自热效应。/Short duration pulse test used to minimize self-heating effect.

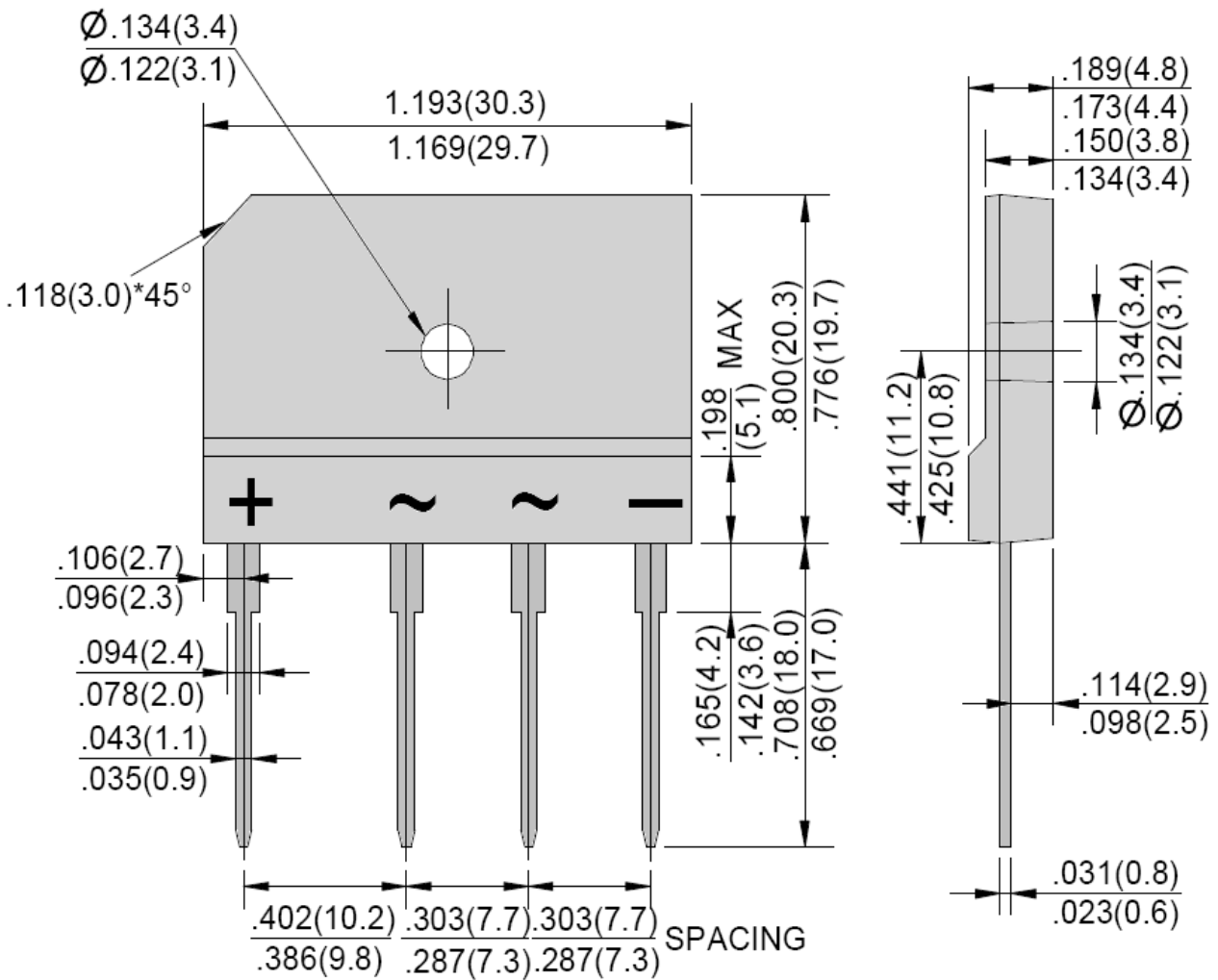
2. 除非特别注明,数值为一个芯片的参数。/ Unless otherwise noted, values for the parameters of a single chip

电参数曲线图 / Electrical Characteristic Curve

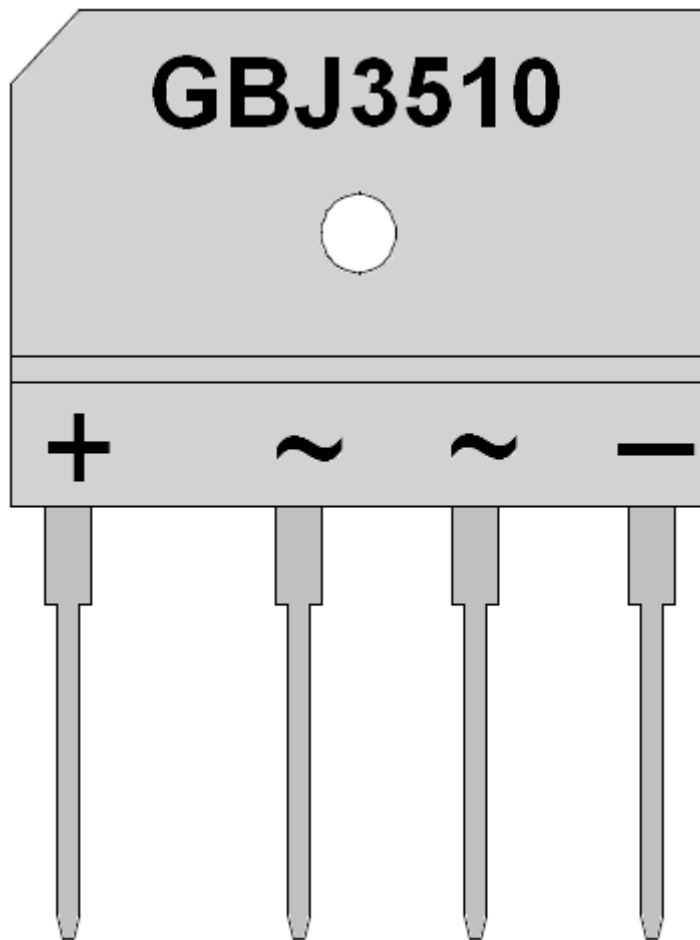


**外形尺寸图 / Package Dimensions**

**GBJ**



印章说明 / Marking Instructions

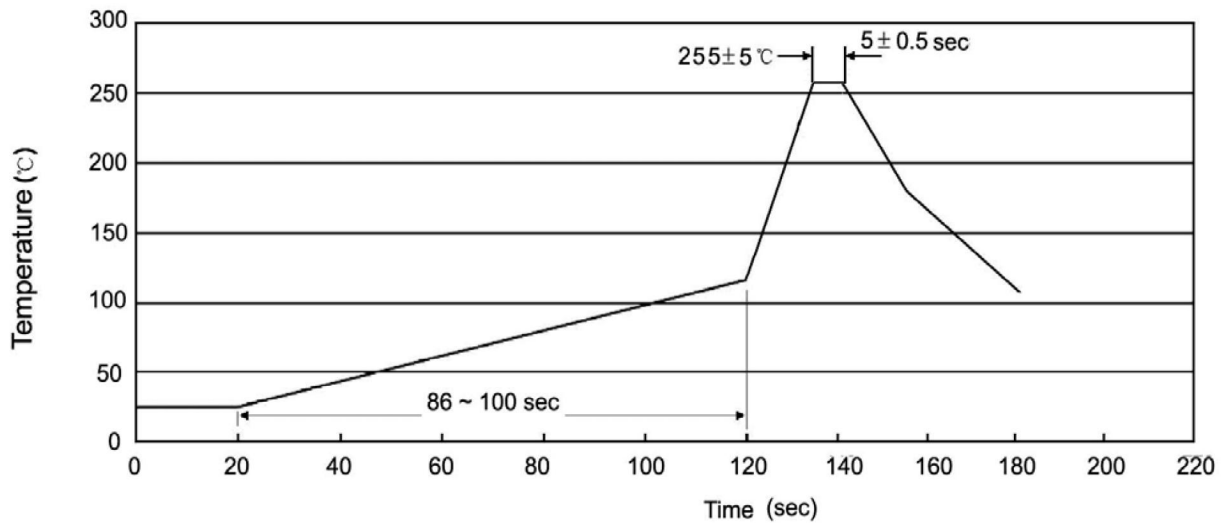


说明：

GBJ3510 : 产品型号  
- AC + : 引脚功能

Note:

GBJ3510 : Product Type  
- AC + : Pin function

**波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)**


说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec；
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

散件包装 / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
GBJ	-	-	250	8	2000	-	315×135×48	330×285×215

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
GBJ	15	40	600	2	1200	471×42×10	500×190×105	525×210×245

**使用说明 / Notices**